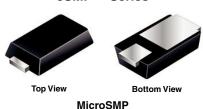


Vishay General Semiconductor

Surface Mount Schottky Barrier Rectifiers

eSMP[™] Series



PRIMARY CHARACTERISTICS				
I _{F(AV)}	2.0 A			
V _{RRM}	20 V, 30 V			
I _{FSM}	30 A			
V _F at I _F = 2.0 A	0.47 V			
T _J max.	150 °C			

TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, dc-to-dc converters, and polarity protection applications.

FEATURES

• Very low profile - typical height of 0.65 mm



Ideal for automated placement

Low forward voltage drop, low power losses

High efficiency

 Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

• Solder dip 265 °C max. 10 s, per JESD 22-A111

 Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC

Halogen-free according to IEC 61249-2-21 definition

MECHANICAL DATA

Case: MicroSMP

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free and RoHS compliant, commercial grade

Terminals: Matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test **Polarity:** Color band denotes the cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	MSS2P2	MSS2P3	UNIT	
Device marking code		22	23		
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	V	
Maximum average forward rectified current (Fig. 1)	I _{F(AV)}	2.0		А	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	30		А	
Operating junction and storage temperature range	T_J, T_{STG}	- 55 to + 150		°C	

MSS2P2 & MSS2P3

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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST C	TEST CONDITIONS		TYP.	MAX.	UNIT
Maximum instantaneous forward voltage ⁽¹⁾	I _F = 1.0 A I _F = 2.0 A	T _A = 25 °C	V _F	0.44 0.52	- 0.60	V
	I _F = 1.0 A I _F = 2.0 A	T _A = 125 °C		0.36 0.47	- 0.55	
Maximum reverse current (2)	Rated V _R	T _A = 25 °C T _A = 125 °C	I _R	15 6.0	250 20	μA mA
Typical junction capacitance	4.0 V, 1 MH	4.0 V, 1 MHz		65	-	pF

Notes

 $^{(1)}$ Pulse test: 300 μs pulse width, 1 % duty cycle

 $^{(2)}$ Pulse test: Pulse width \leq 40 ms

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	MSS2P2	MSS2P3	UNIT	
Typical thermal resistance ⁽¹⁾	$egin{array}{c} {\sf R}_{ heta {\sf JA}} \ {\sf R}_{ heta {\sf JL}} \ {\sf R}_{ heta {\sf JC}} \end{array}$	105 15 20		°C/W	

Note

⁽¹⁾ Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 6.0 x 6.0 mm copper pad areas. $R_{\theta JL}$ is measured at the terminal of cathode band. $R_{\theta JC}$ is measured at the top center of the body

ORDERING INFORMATION (Example)					
PREFERRED P/N	DELIVERY MODE				
MSS2P3-M3/89A	0.006	89A	4500	7" diameter plastic tape and reel	

RATINGS AND CHARACTERISTICS CURVES

(T_A = 25 °C unless otherwise noted)

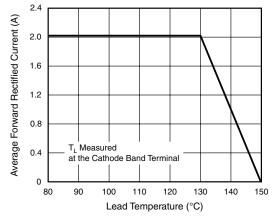


Figure 1. Forward Current Derating Curve

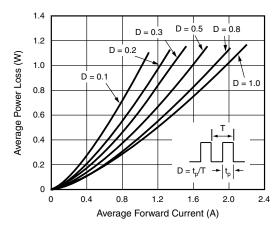


Figure 2. Forward Power Loss Characteristics



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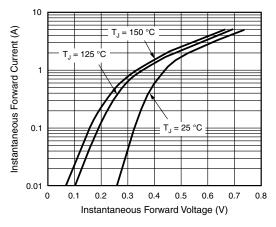


Figure 3. Typical Instantaneous Forward Characteristics

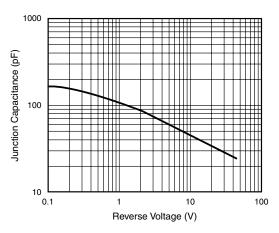


Figure 5. Typical Junction Capacitance

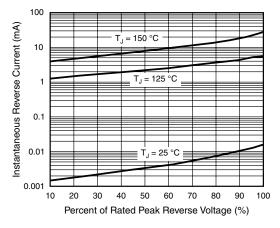


Figure 4. Typical Reverse Characteristics

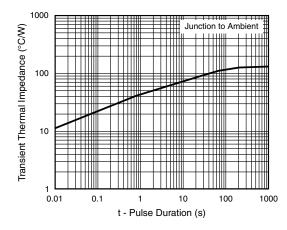
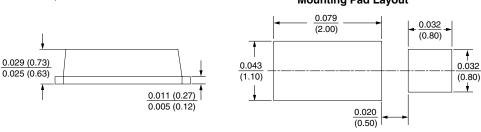


Figure 6. Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

MicroSMP 0.059 (1.50) 0.030 (0.75) Cathode Band 0.043 (1.10) 0.022 (0.55) 0.055 (1.40) 0.047 (1.20) 0.030 (0.75) 0.039 (0.98) 0.031 (0.78) 0.022 (0.55) 0.091 (2.30) 0.083 (2.10) 0.106 (2.70) 0.091 (2.30) **Mounting Pad Layout**





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